

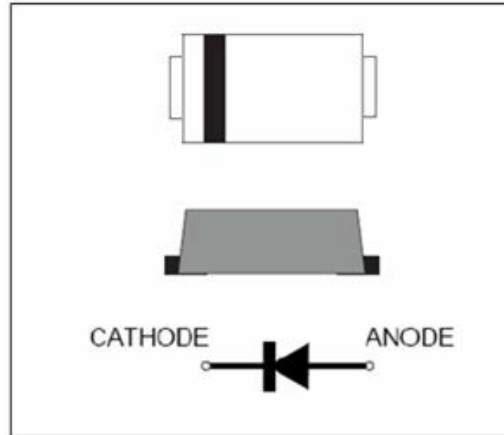
# MBR0520E thru MBR0540E

## Schottky Barrier Rectifiers

Reverse Voltage 20 to 40V Forward Current 0.5A

### FEATURES

- \* Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- \* Low power loss,high efficiency
- \* For use in low voltage high frequency inverters, free wheeling,and polarity protection applications
- \* Guardring for over voltage protection
- \* High temperature soldering guaranteed: 260°C/10 seconds at terminals



We declare that the material of product is Halogen free (green epoxy compound)

### Mechanical Data

**Case:** SOD-323HE

molded plastic over sky die

**Terminals:** Plated leads, solderable per MIL-STD-750, Method 2026

**Polarity:** Color band denotes cathode end

**Mounting Position** Any

**Weight:** 0.0053 g

**Handling precaution**None

### 1.Electrical Characteristic

**Maximum & Thermal Characteristics Ratings** at 25°C ambient temperature unless otherwise specified.

| Parameter Symbol   | symbol          | MBR0520E    | MBR0530E | MBR0540E | Unit |
|--|-----------------|-------------|----------|----------|------|
| device marking code  |                 | 052         | 053      | 054      |      |
| Maximum repetitive peak reverse voltage  | $V_{RRM}$       | 20          | 30       | 40       | V    |
| Maximum RMS voltage  | $V_{RMS}$       | 14          | 21       | 28       | V    |
| Maximum DC blocking voltage  | $V_{DC}$        | 20          | 30       | 40       | V    |
| Maximum average forward rectified current at TC = 75°C   | $I_{F(AV)}$     | 0.5         |          |          | A    |
| Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method) | $I_{FSM}$       | 22          |          |          | A    |
| Typical thermal resistance (Note 1)  | $R_{\theta JA}$ | 210         |          |          | °C/W |
|  | $R_{\theta JL}$ | 70          |          |          |      |
| Operating junction temperature range   | $T_J$           | -55 to +125 |          |          | °C   |
| storage temperature range  | $T_{STG}$       | -55 to +150 |          |          | °C   |

**Electrical Characteristics Ratings** at 25°C ambient temperature unless otherwise specified.

| Parameter Symbol  | symbol | MBR0520E  | MBR0530E    | MBR0540E   | Unit |
|---|--------|-----------|-------------|------------|------|
| Maximum instantaneous forward voltage at ( $I_F = 0.5 A, T_J = 25^\circ C$ )                      | $V_F$  | 0.43      | 0.45        | 0.55       | V    |
| Maximum DC reverse current at rated DC blocking voltage $T_A = 25^\circ C$<br>$T_J = 100^\circ C$ | $I_R$  | 0.25<br>8 | 0.130<br>10 | 0.03<br>10 | mA   |
| Typical junction capacitance at 4.0V, 1MHz  | $C_J$  | 160       |             |            | PF   |

NOTES:

1. 8.0mm<sup>2</sup> (.013mm thick) land areas



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## 2. Ratings and Characteristic Curves (TA = 25°C unless otherwise noted)

Fig. 1 - Forward Current Derating Curve

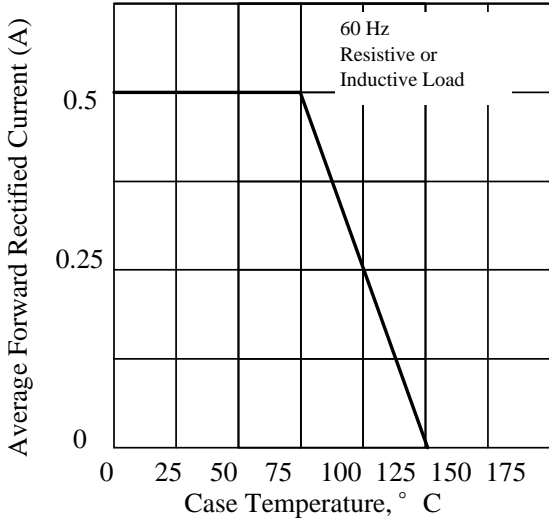


Fig. 2 - Maximum Non-repetitive Peak Forward Surge Current

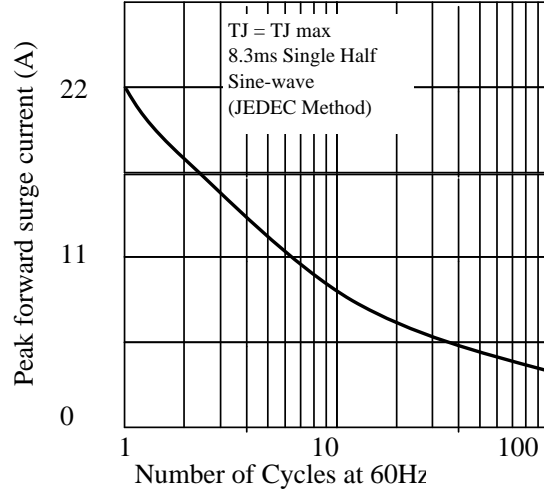


Fig. 3 - Typical Instantaneous Forward Characteristics

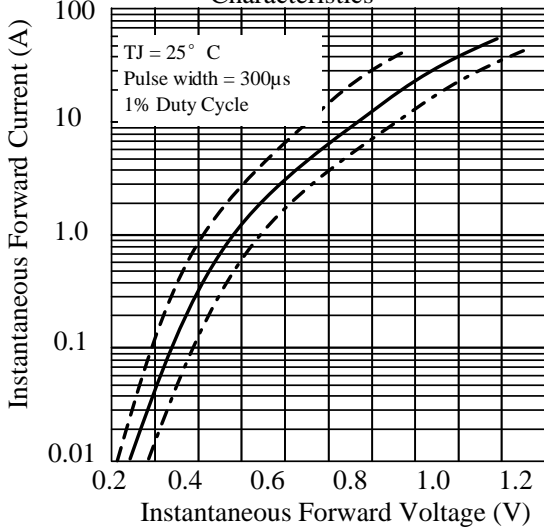


Fig. 4 - Typical Reverse Characteristics

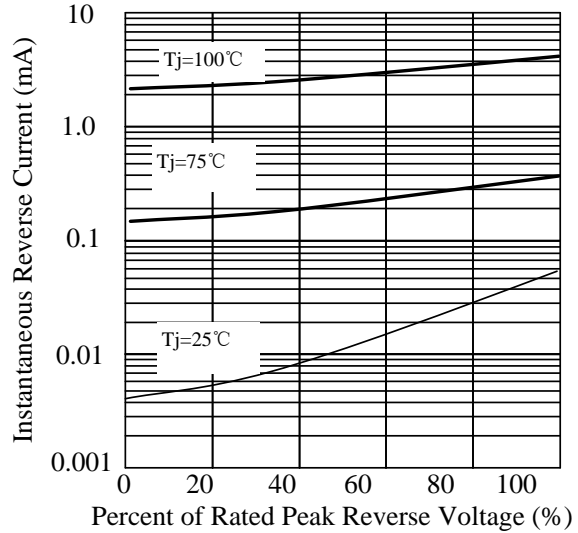


Fig. 5 - typical transient thermal impedance

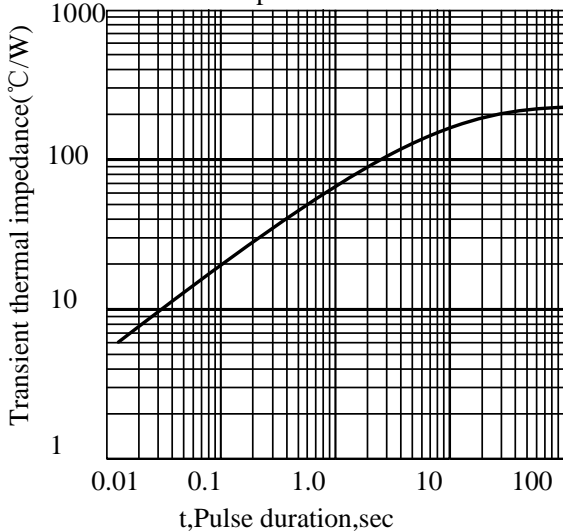
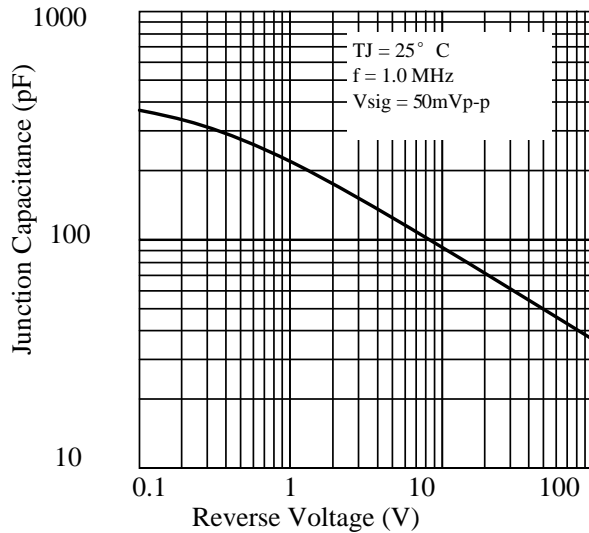
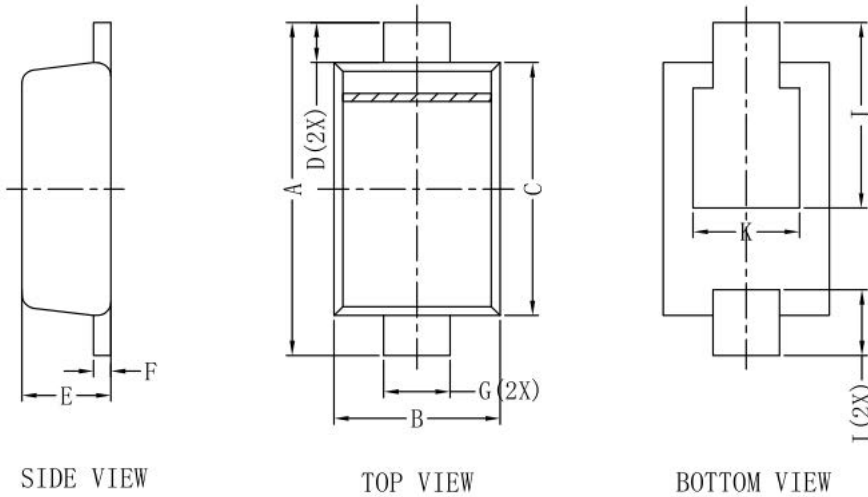


Fig. 6 - Typical Junction Capacitance



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## 3. dimension:



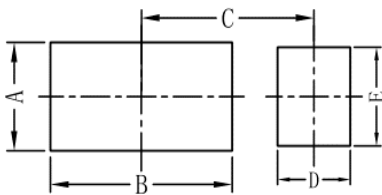
| SOD323HE             |      |      |      |
|----------------------|------|------|------|
| DIM                  | MIN  | MAX  | Typ. |
| A                    | 2.30 | 2.70 | 2.55 |
| B                    | 1.20 | 1.35 | 1.25 |
| C                    | 1.75 | 1.95 | 1.90 |
| D                    | -    | -    | 0.30 |
| E                    | 0.55 | 0.75 | 0.67 |
| F                    | 0.10 | 0.20 | 0.15 |
| G                    | 0.45 | 0.65 | 0.50 |
| I                    | 0.40 | 0.70 | 0.50 |
| J                    | 1.15 | 1.55 | 1.40 |
| K                    | -    | -    | 0.80 |
| All Dimensions in mm |      |      |      |

### GENERAL NOTES

1. Top package surface finish  $Ra0.4 \pm 0.2\mu m$
2. Bottom package surface finish  $Ra0.7 \pm 0.2\mu m$

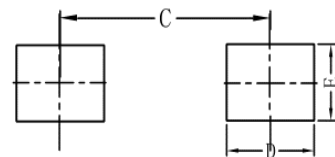
### Suggested solder pad layout

#### RECOMMENDED PAD



| SOD323HE |      |
|----------|------|
| DIM      | (mm) |
| A        | 1.1  |
| B        | 2.0  |
| C        | 1.9  |
| D        | 0.8  |
| E        | 1.0  |

#### COMPATIBLE PAD



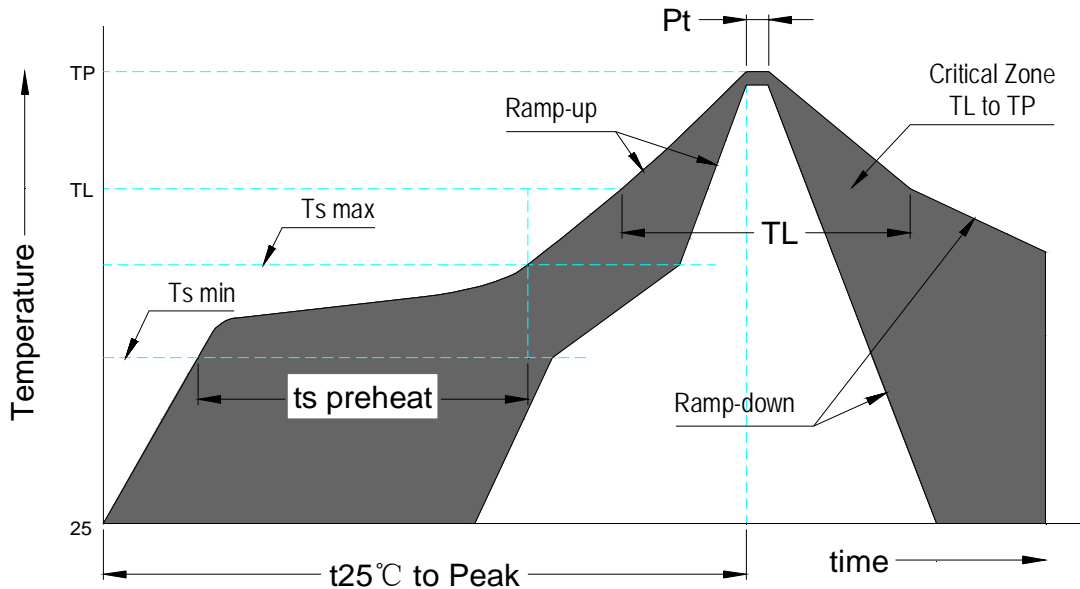
| SOD323HE |      |
|----------|------|
| DIM      | (mm) |
| D        | 1.0  |
| E        | 0.8  |
| C        | 2.4  |



# MBR0520E thru MBR0540E

## 5.Suggested thermal profile for soldering process

1. Storage environment : Temperature=5~40°C Humidity=55±25%
2. Reflow soldering of surface-mount device



### 3. Reflow soldering

| Profile Feature   | Soldering Condition |
|---|---------------------|
| Average ramp-up rate(T <sub>L</sub> to T <sub>P</sub> )     | <3°C/sec            |
| Preheat   |                     |
| - Temperature Min(T <sub>smin</sub> )                       | 150°C               |
| - Temperature Max(T <sub>smax</sub> )                       | 200°C               |
| - Time(min to max)(t <sub>s</sub> )                         | 60~120sec           |
| T <sub>smax</sub> to T <sub>L</sub>                         |                     |
| - Ramp-up Rate  | <3sec               |
| Time maintained above:                                      |                     |
| - Temperature (T <sub>L</sub> )                             | 217°C               |
| - Time(t <sub>L</sub> )                                     | 60-260sec           |
| Peak Temperature(T <sub>P</sub> )                           | 255 -0/+5°C         |
| Time within 5°C of actual Peak Temperature(T <sub>P</sub> ) | 10~30sec            |
| Ramp-down Rate  | <6°C/sec            |
| Time 25°C to Peak Temperature                               | <6minutes           |



## MBR0520E thru MBR0540E

### 6.High reliability test capabilities

| Item Test                     | Condition   | Reference                  |
|-------------------------------|---|----------------------------|
| Solder Resistance             | at 260±5°C for 10±2sec immerse  | MIL-STD-750D METHOD-2031   |
| Solderability                 | at 245±5°C for 5 sec  | MIL-STD-202F METHOD-208    |
| High Temperature Reverse Bias | V <sub>R</sub> =80% rate at T <sub>j</sub> =125°C for 168hrs                        | MIL-STD-750D METHOD-1038   |
| Forward Operation Life        | Rated average rectifier current<br>T <sub>A</sub> =25°C for 500hrs                  | MIL-STD-750D METHOD-1027   |
| Intermittent Operation Life   | T <sub>A</sub> =25°C , I <sub>F</sub> =I <sub>o</sub>                               | MIL-STD-750D METHOD-1036   |
| Pressure Cooker               | 15P <sub>SIG</sub> at T <sub>A</sub> =121°C for 4hrs                                | JESD22-A102                |
| Temperature Cycling           | -55°C to +125°C dwelled for 30 min.<br>and transferred for 5min. Total 10<br>cycles | MIL-STD-750D METHOD-1051   |
| Thermal Shock                 | 0°C for 5min. Rise to 100°C for 5min.<br>Total 10 cycles                            | MIL-STD-750D METHOD-1056   |
| Forward Surge                 | 8.3ms single half sine-wave<br>superimposed on rated load,one surge                 | MIL-STD-750D METHOD-4066-2 |
| Humidity                      | at T <sub>A</sub> =85°C , R <sub>H</sub> =85% for 1000hrs                           | MIL-STD-750D METHOD-1021   |
| High Temperature Storage Life | at 150°C for 1000hrs  | MIL-STD-750D METHOD-1031   |

